



## **TEA ADDS BUSINESS DEVELOPMENT PROFESSIONALS**

*Bill Ribble and Doug Greenwood Join TEA*

San Jose, California, May 5, 2010 – Thermal Engineering Associates announced today the addition of two business development professionals to its staff. Bill Ribble and Doug Greenwood have joined the company as Directors of Business Development in Thermal Test Chips and Thermal Test Systems, respectively.

Ribble brings experience in sales, marketing, and management in wireless semiconductor, automated test equipment, and management consulting companies over the past 35 years. “I am happy to be joining Bernie Siegal, this time at TEA,” said Ribble, “where I can bring my sales and marketing skills to bear on a great range of thermal test chip opportunities.”

Doug Greenwood has experience in engineering, sales, marketing and management through numerous Silicon Valley companies over the past more than 30 years. His relationship with TEA founder and owner, Bernie Siegal spans more than 25 years. His specialty is selling capital equipment and in this regard he will be responsible in his new position for all TEA thermal test equipment sales in the USA and Canada.

### **About Thermal Engineering Associates:**

TEA and its president, Bernie Siegal, have been providing thermal test and measurement hardware, software, and consulting services since 1973. Siegal has been chairman of the JEDEC JC15 committee and is the principle author of many MILSTD 750 thermal test methods. All major semiconductor companies, packaging companies, and many system level OEMs have utilized TEA equipment and/or services during its long history. Siegal is a founding member of IEEE SEMI-THERM and has delivered numerous papers and articles on thermal testing, simulation, and evaluation methods and techniques and is frequently sought out as a lecturer and expert in the field. [www.thermeng.com](http://www.thermeng.com).

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